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BGA/CSP DEVELOPMENT UPDATE SERVICE

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The second quarterly BGA/CSP update for 2003 features special coverage of flip chip substrates, with descriptions of new high-density core substrates offered by companies worldwide. Industry trends for laminate flip chip substrates are discussed, including body size, core thickness, substrate finish, and substrate price trends. A market forecast for PBGAs shows growth for both flip chip and wire bond packages. A special section on IC package assembly price trends is included in the report. Average assembly prices are provided for QFPs, wire bond and flip chip PBGAs, laminate substrate CSPs, lead frame-based CSPs, and stacked die CSPs. Sharp's new mobile phone containing a CCD camera is described. New package developments are presented, including ChipPAC's stacked die CSP and joint activities to study tin whisker growth in lead-free packages.

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